

FIG.1E

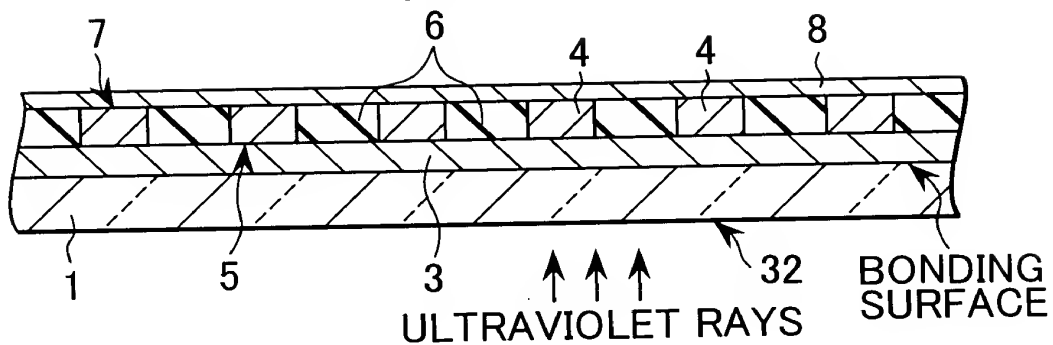


FIG.1F

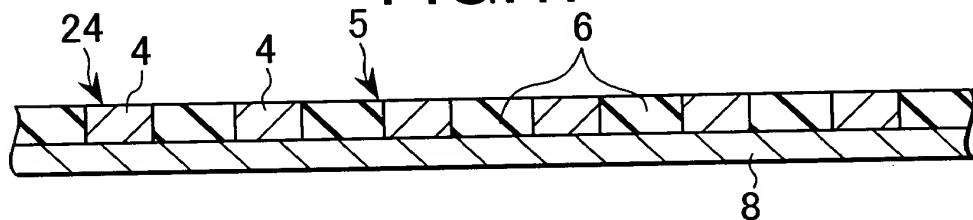


FIG.1G

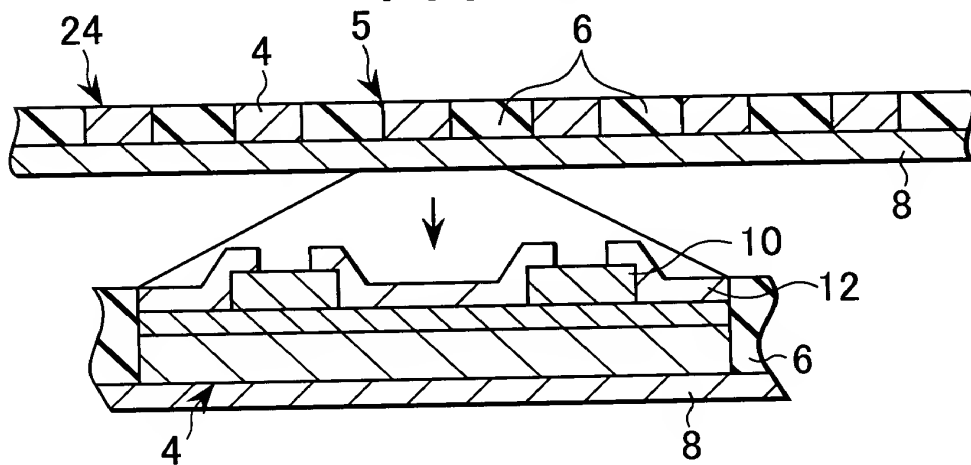
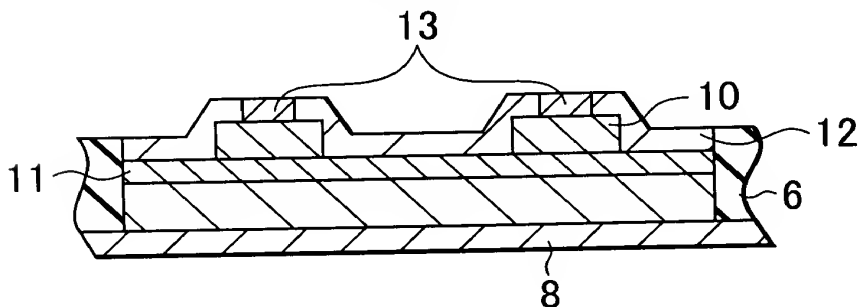


FIG.1H



A cross-sectional view of a substrate 4 with a series of rectangular blocks 5 on top. The blocks 5 are separated by grooves 6. A dicing process is shown with a dicing tool 9 and a dicing direction indicated by an arrow labeled "DICING". The substrate 4 has a bottom layer 8 and a top layer 16. A dimension 34 is indicated for the width of the blocks 5.

FIG.2

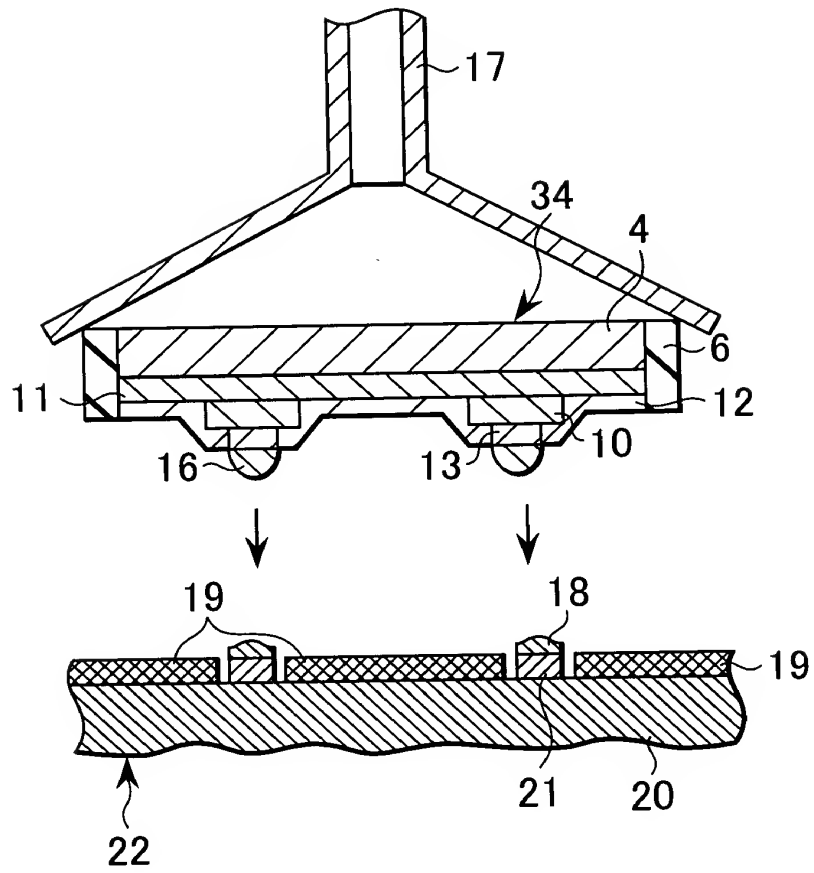


FIG.3

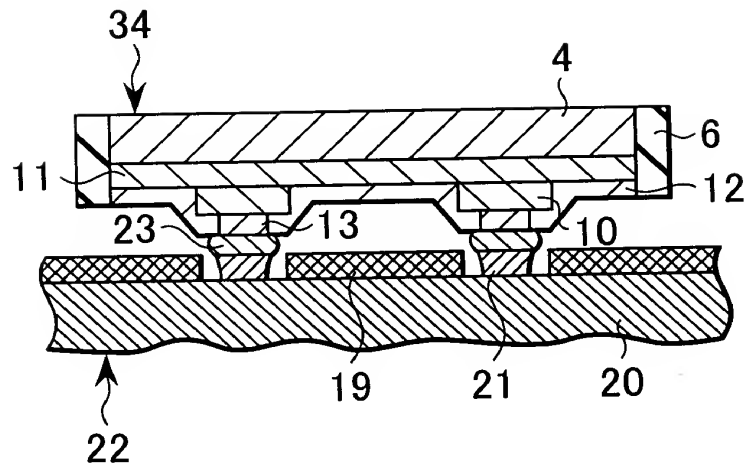


FIG.4

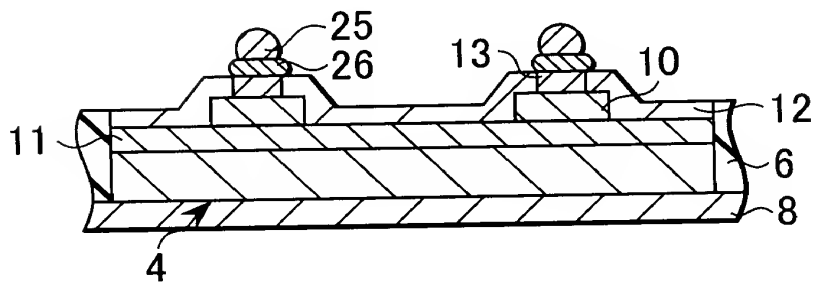


FIG.5

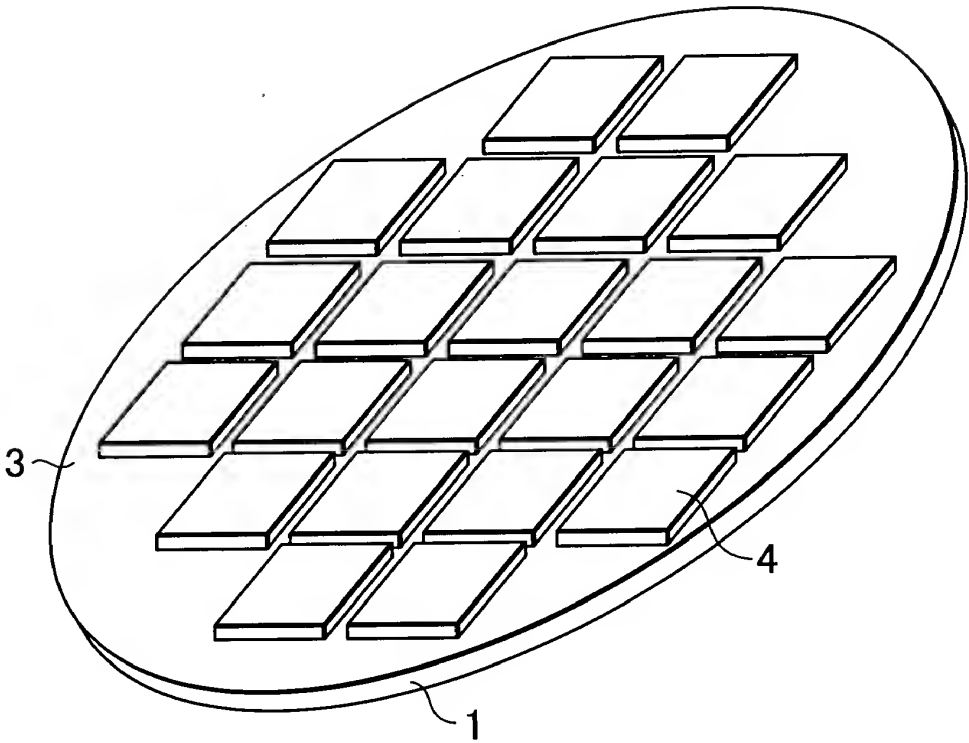


FIG.6

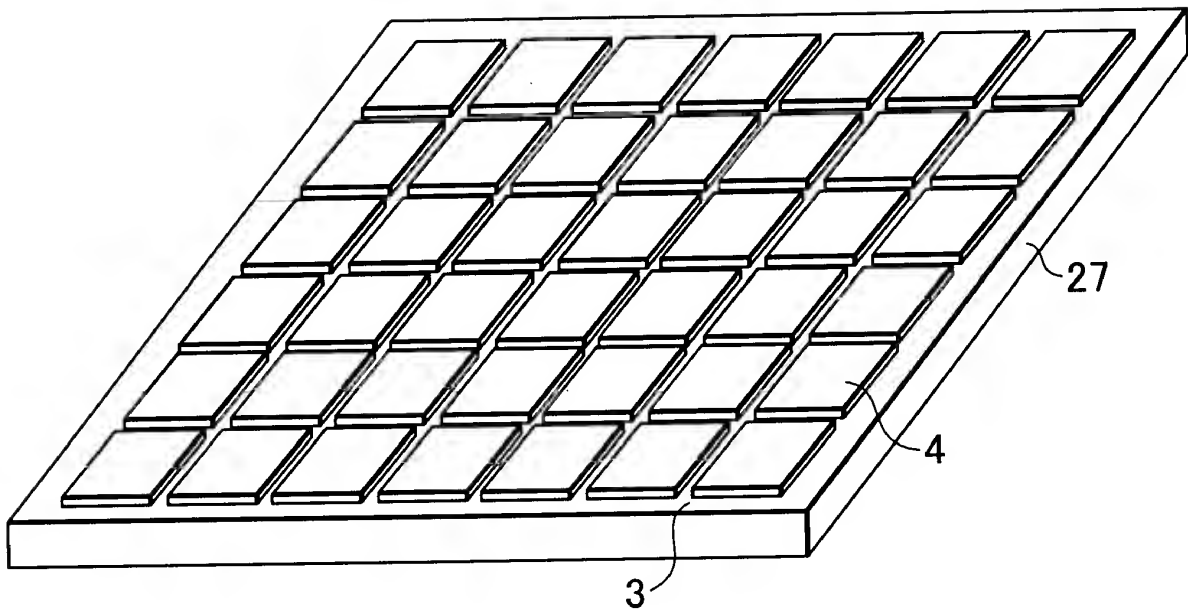


FIG.7

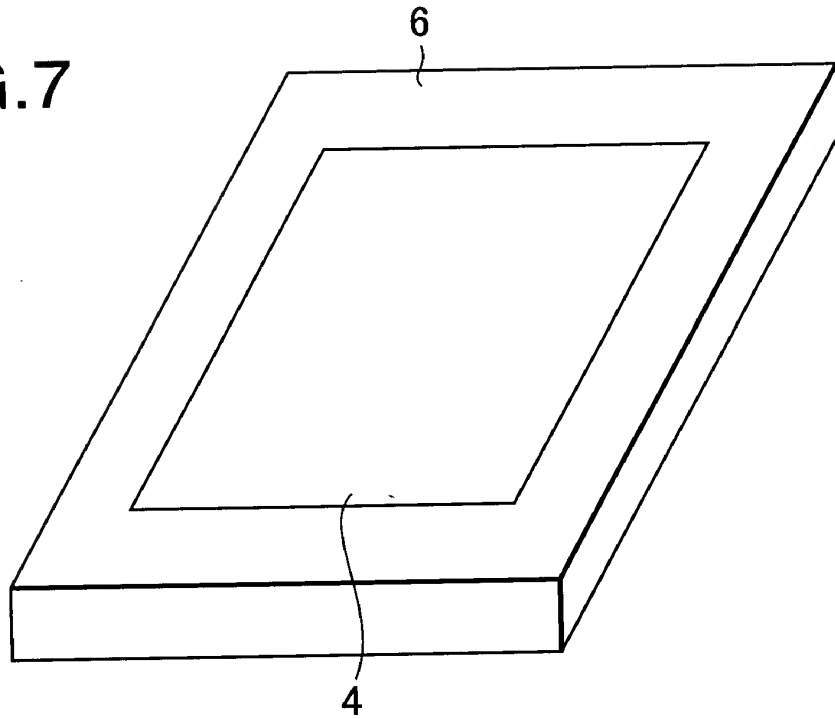


FIG.8

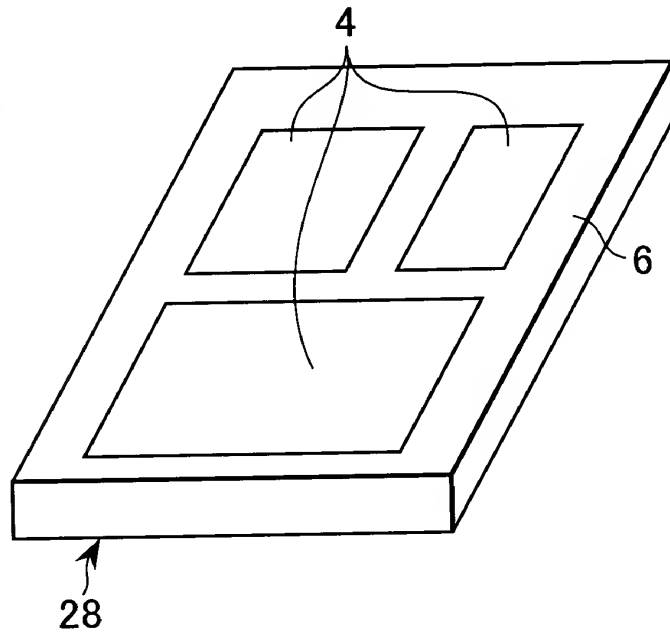


FIG.9

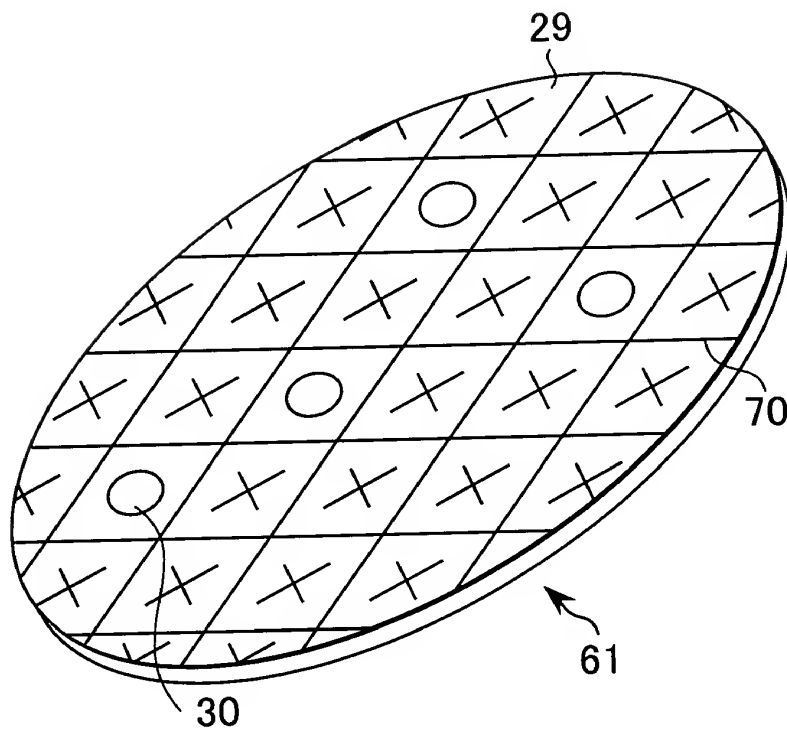


FIG.10A

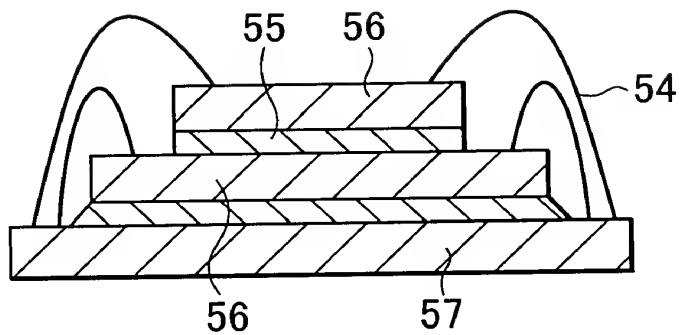


FIG.10B

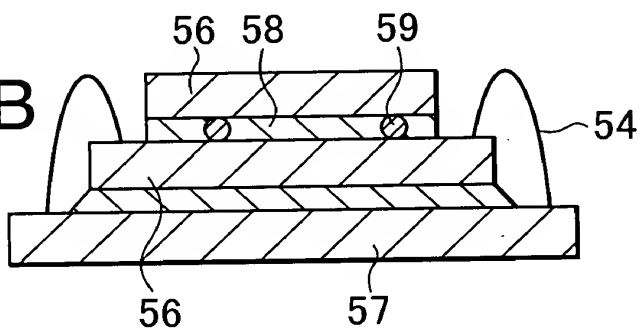


FIG.10C

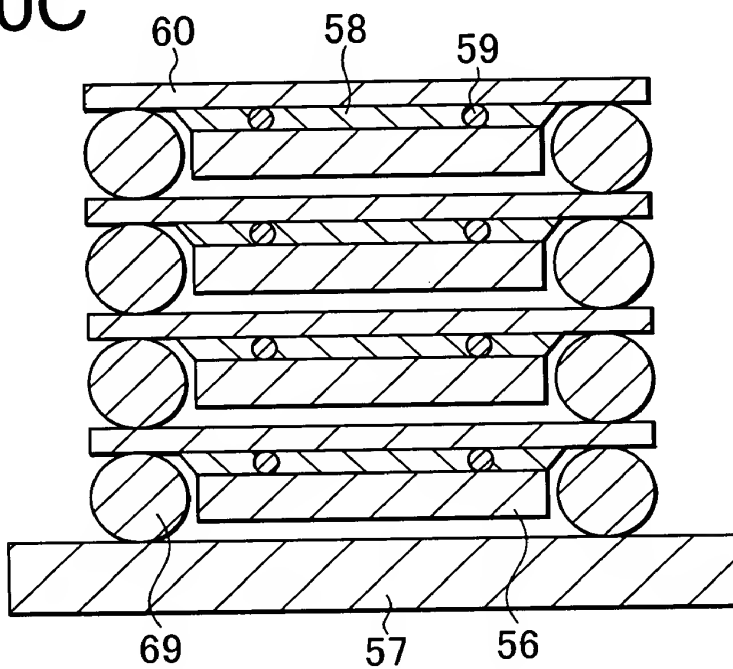


FIG.11A

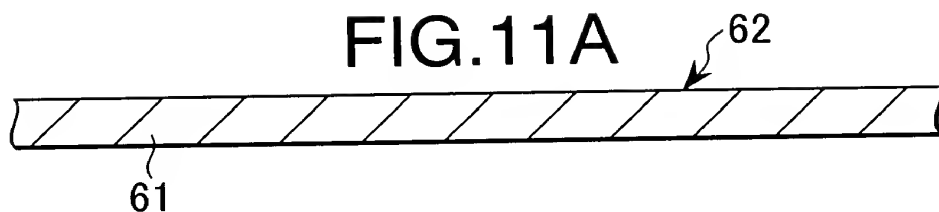


FIG.11B

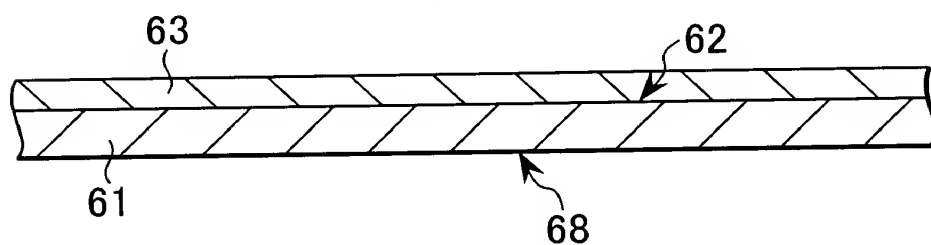


FIG.11C

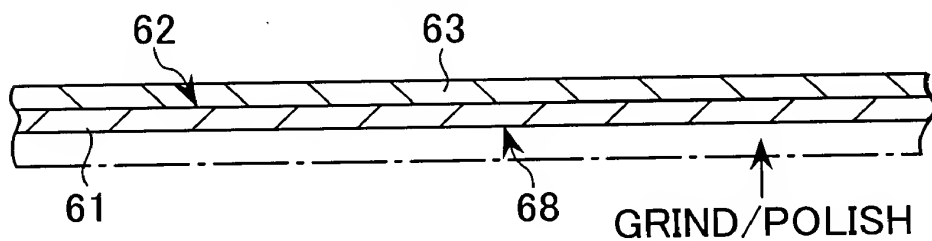


FIG.11D

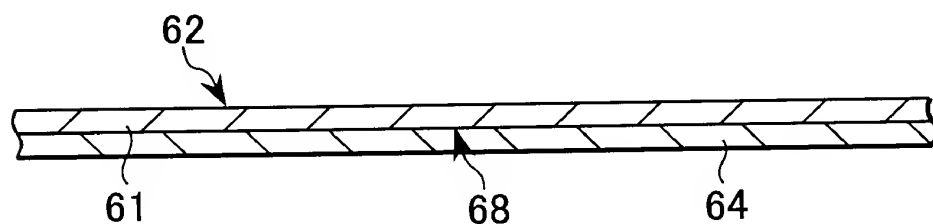


FIG.11E

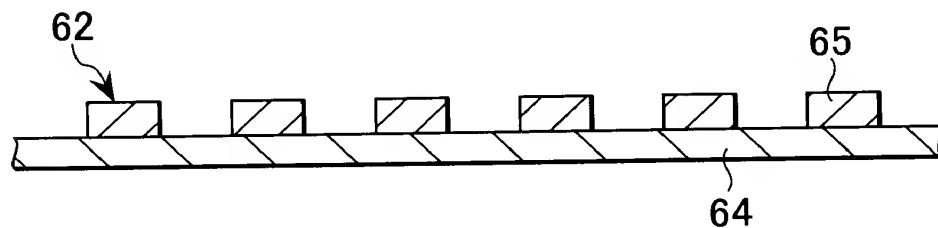


FIG.12A

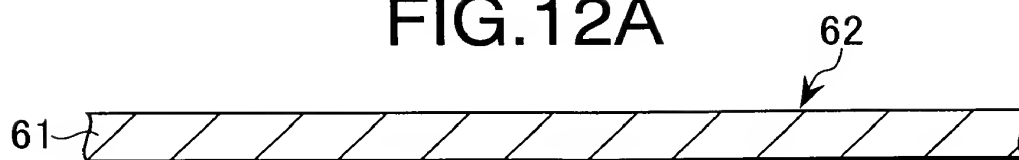


FIG.12B

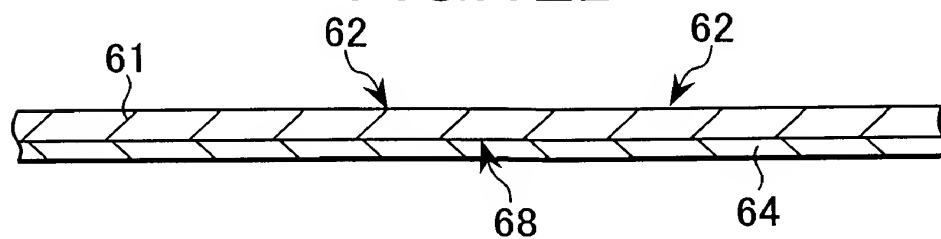


FIG.12C

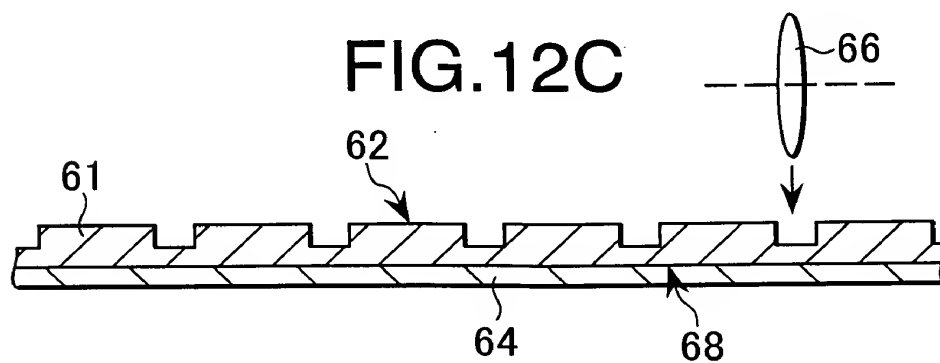


FIG.12D

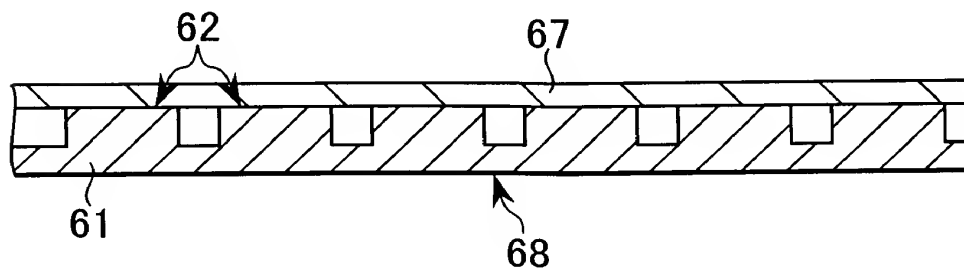


FIG.12E

